

of electrically conducting material, preferably spring steel or the like. The plate 20 has a central portion with two aligned longitudinal slots 21 and 23 in it. These slots are placed over a pair of rivets 24 and 25 attached to the upper layer 10 of the laminated IC card. The heads of the rivets 24 and 25 extend over the edges of the slots 21 and 23, as illustrated most clearly in FIG. 7. Consequently, the plate 20 is movable from the position shown in FIG. 3 to the position shown in FIG. 4 and back again, with the lengths of the slots 21 and 23 and the positions of the rivets 24 and 25 determining the limits of movement which are illustrated in FIGS. 3 and 4.

The plate 20 has five outwardly extending cover flanges or plates 30, 32, 34, 36, and 38 which, in the closed position of FIG. 3, overlie the removable IC unit modules 40, 42, 44, 46, and 48, respectively. Each of these cover flanges 30, 32, 34, 36, and 38, has a corresponding downwardly projecting dimple, such as the dimples 35, 37, and 33, shown in FIGS. 5, 6, and 9, respectively. These dimples correspond with mating semispherical recesses 41, 43, 45, 47, and 49, located in the center of the removable IC module units 40, 42, 44, 46, and 48, respectively. The result is that when the cover plate 20 is moved to the position shown in FIG. 3, the dimples under each of the extending cover flanges, such as 34 and 36, shown in FIGS. 5 and 6, press into the mating recesses, such as 45 and 47, of the IC module located beneath them to press the corresponding module in place. This holds it in tight electrical engagement with the network bus conductors 70, 80, 90, and 100, and also prevents the removable IC module units from falling out of the recesses in the top layer 10 of the card.

When it is desired either to remove a removable IC module unit from the card or to place a new one into an open receptacle the cover plate 20 is moved to the position shown in FIG. 4. In this position, all of the module positions are exposed. It should be noted that when the cover plate 20 is moved between the two positions shown in FIGS. 3 and 4, the dimples, such as 35 and 37, ride up onto the surface of the removable modules and also onto the surface of the card 10 bending the corresponding cover flanges 30, 32, 34, 36, and 38 upwardly against the spring action of the material out of which the plate 20 is made. When the plate is in the position shown in FIG. 3, the nesting of the dimples, such as 35 and 37, into the corresponding recesses, such as 45 and 47, of the underlying removable IC module units acts as a detent to hold the plate 20 against accidental dislodgement.

FIG. 6 illustrates in detail the interrelationship between the cover plate 20 and the cover flanges, such as the cover flange 36 with respect to the removable IC module unit 46 and the receptacle 56. Receptacles such as the receptacles 54 and 56, shown in FIGS. 5 and 6, correspond with each of the removable IC module units 40, 42, 44, 46, and 48, in the positions shown in FIGS. 3 and 4. One or more of these module units may be used at any time, depending upon the number of different programs and the number of different host computers with which the system is designed to interact.

From the foregoing, it can be seen that a single IC card, such as the card shown in FIGS. 3 through 11, is capable of replacing six individual separate IC cards of the type commonly in use today. Furthermore, it is possible to change the various programs or host computer systems with which the card is used, at any time

simply by placing a new removable IC module unit or token into one of the corresponding receptacles, or by replacing one of the IC module units 40, 42, 44, 46, and 48 with a different one.

To further expand the multiple on line capability of the system, a magazine for holding several cards 10 may be used. Such a magazine can be used to place multiple cards, each with several modules on it, in position for use with a single card reader. The cards may be interconnected with buses in the magazine, or they each may simply be available for individual presentation to a card reader 12.

The foregoing description of the preferred embodiment of the invention should be considered as illustrative of the invention and not as limiting. Various changes and modifications will occur to those skilled in the art without departing from the true scope of the invention as defined in the appended claims. For example, the illustration used shows four bus conductors 70, 80, 90, and 100, as the network bus conductors. This number of conductors clearly can be varied in accordance with the operating conditions of the system. For example, a single conductor may be used for multiplex operations, and for parallel operations the number of conductors may be increased or decreased in accordance with the system requirements. In addition, the technique for ensuring proper orientation of the removable IC unit modules may be changed from the mating notches and projection structures which are illustrated in the drawings. The configuration of the cover plate 20 also may be varied, as well as the manner in which the cover plate is attached to the layer 10 of the laminated IC card to permit the sliding movement which is shown. All such changes and others which will occur to those skilled in the art are considered to be clearly within the scope of this invention.

I claim:

1. An IC card including in combination:
 - a card body of a predetermined thickness having a first surface and having a network bus conductor therein at a distance from said first surface which is less than said predetermined thickness;
 - an inlaid information processing unit in said card body having external signal connection terminals on an exposed face thereof at said first surface of said card body and electrically interconnected with said network bus conductor;
 - at least one open receptacle extending from the first surface of said card body to a depth to expose said network bus conductor therein for electrical contact with conductive terminals of a removable information processing unit configured to fit into said receptacle and
 - retaining means comprising cover means extending over said receptacle in a first position thereof and movable to a second position to expose said receptacle for releasably retaining removable information processing units in said receptacle.
2. The combination according to claim 1 further including means associated with said receptacle for ensuring a predetermined orientation of removable information processing units placed into said receptacle.
3. The combination according to claim 2 wherein said inlaid information processing unit includes a signal processing integrated circuit.
4. The combination according to claim 3 wherein said orienting means comprises mating projections and